

SMQ32S material declaration

Part weight: 158 mg



RoHS compliant



Pb free



REACH compliant

RoHS (2015/863/EU) compliant

Component Name	Sub-part Name	Material Name	Mass (mg)	Substance Name	CAS No.	Mass (mg)	Content (wt%)	Purpose of use
Crystal blank		Quartz	2.4	Quartz (SiO ₂)	14808-60-7	2.400	100.0000	Main material
Can		Cu Alloy	33.123	Copper (Cu)	7440-50-8	21.30	64.0000	Main material
				Zinc (Zn)	7440-66-6	5.851	17.5750	Main material
	Nickel (Ni)			7440-02-0	5.850	18.0000	Main material	
	Manganese (Mn)			7439-96-5	0.081	0.2500	Alloy material	
	Iron (Fe)			7439-89-6	0.041	0.1250	Alloy material	
	Plating	Ni	3.5	Nickel (Ni)	7440-02-0	3.500	100.0000	Main material
Base	Shell	Alloy 42	4.9	Iron (Fe)	7439-89-6	2.837	57.9000	Main material
				Nickel (Ni)	7440-02-0	2.009	41.0000	Main material
				Cobalt (Co)	7440-48-4	0.049	1.0000	Alloy material
				Carbon (C)	7440-44-0	0.005	0.1000	Alloy material
	Wiring	Kovar	2.19	Iron (Fe)	7439-89-6	1.170	53.4400	Main material
				Nickel (Ni)	7440-02-0	0.635	29.0000	Main material
			Cobalt (Co)	7440-48-4	0.372	17.0000	Main material	
			Manganese (Mn)	7439-96-5	0.011	0.5000	Alloy material	
			Carbon (C)	7440-44-0	0.001	0.0600	Alloy material	
	Glass	Glass	2.8	Borosilicate Glass Al ₂ B ₂ O ₈ Si	65997-17-3	2.800	100.0000	Glass material
	Under plating	Cu	0.4	Copper (Cu)	7440-50-8	0.400	100.0000	Main material
	Solder plating	Sn-Pb	1.75	Lead (Pb)	7439-92-1	1.570	89.7143	Main material
				Tin (Sn)	7440-31-5	0.180	10.2857	Solder material
Internal solder		Pb-Sn-Ag	0.4	Lead (Pb)	7439-92-1	0.370	92.4000	Main material
				Tin (Sn)	7440-31-5	0.020	4.9000	Solder material
				Silver (Ag)	7440-22-4	0.011	2.7000	Solder material
Electrode	Electrode 1	Ag	0.0129	Silver (Ag)	7440-22-4	0.013	100.0000	Main material
	Electrode 2	Sn	0.0048	Tin (Sn)	7440-31-5	0.005	100.0000	Main material
	Electrode 3	Cr	0.0035	Chromium (Cr)	7440-47-3	0.004	100.0000	Main material
Lead frame		Alloy 42	17.4	Iron (Fe)	7439-89-6	10.057	57.8000	Main material
				Nickel (Ni)	7440-02-0	7.134	41.0000	Main material
				Manganese (Mn)	7439-96-5	0.139	0.8000	Alloy material
	Silicon (Si)			7440-21-3	0.052	0.3000	Alloy material	
	Carbon (C)			7440-44-0	0.009	0.0500	Alloy material	
	Phosphorus (P)			7723-14-0	0.004	0.0250	Alloy material	
	Sulfur (S)	7704-34-9	0.004	0.0250	Alloy material			
	Under plating	Ni	0.172	Nickel (Ni)	7440-02-0	0.172	100.0000	Main material
	Surface plating	Sn	0.843	Tin (Sn)	7440-31-5	0.843	100.0000	Main material
Mold resin		Resin	86.100	Fused silica	60676-86-0	64.500	73.3039	Main material
				Aluminium hydroxide	21645-51-2	8.600	9.7800	Main material
				Epoxy resin	29690-82-2	9.500	10.7500	Resin material
				Phenol hardener	9003-35-4	4.800	5.380	Resin material
				Carbon black	1333-86-4	0.700	0.7800	Resin material

* Exemptions from RoHS: No 7 (a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)